

Supplemental Application Data Sheet

Application Information

Application number:: 10/763,561
Filing Date:: 01/22/04
Application Type:: Regular
Subject Matter:: Utility
Suggested Group Art Unit:: N/A 2819
CD-ROM or CD-R?:: None
Sequence submission?:: None
Computer Readable Form (CRF)?:: No
Title:: DISTRIBUTED CURRENT SOURCES FOR
FOLDING ADC AMPLIFIER STAGES
Attorney Docket Number:: 08211/0200350-US0/P05787
Request for Early Publication?:: No
Request for Non-Publication?:: Yes
Total Drawing Sheets:: 6
Small Entity?:: No
Petition included?:: No
Secrecy Order in Parent Appl.?:: No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: US
Status:: Full Capacity
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Country of Residence:: Germany US

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Correspondence Information

Correspondence Customer Number:: 38845

Representative Information

Representative Customer Number:: 38845

Assignee Information

Assignee name:: National Semiconductor Corporation

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